

8通道爆管驱动器

查询样品: **TPIC71008-Q1**

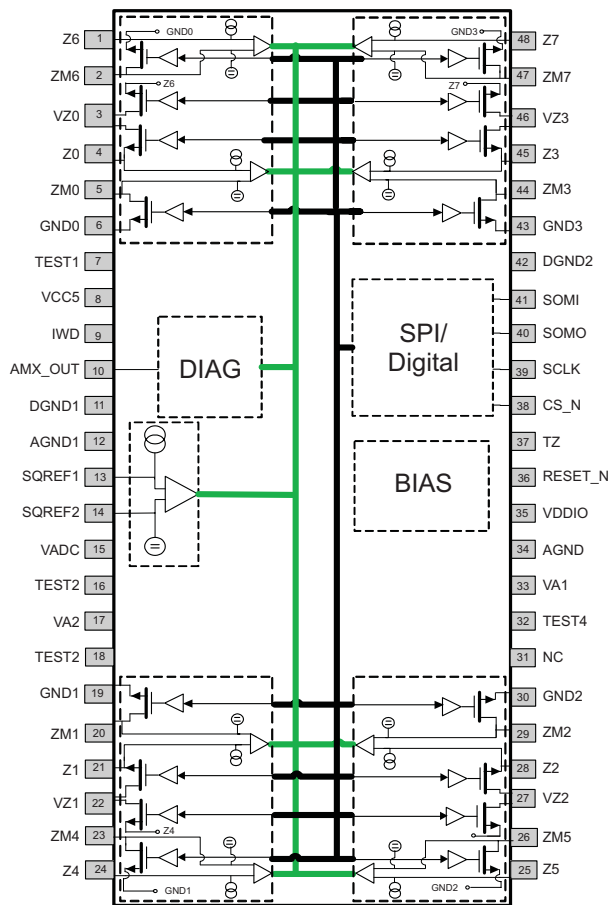
特性

- 针对气囊应用的**8**通道爆管驱动器
- 环路诊断监控和报告
- 两个逻辑输入为启用/禁用部署提供独立的动力恢复逻辑
- **8**个独立的热保护高侧驱动器，可为每个爆管负载提供部署或诊断其电流水平
- **8**个独立的雪崩电压及热保护低侧驱动器，可从每个爆管负载吸收部署或诊断其电流水平。
- 每个输出支持 **1.2 A/1.75 A** 的点火电流，通常持续 **2 ms/0.5 ms**
- **SPI** 从接口支持具有奇偶校验的串行总线通信
- 点火 **VZx** 电压范围为 **10 V** 至 **35 V** 之间，瞬时电压达 **40 V**
- 可编程点火时间高达 **8.2 ms**
- 所有部署环路的通用负载电流设置均采用寄存器
- 每个部署环路采用寄存器设置单个点火电流定时器限制
- 点火电流定时器可监控每个部署环路部署时间的点火电流
- 高低侧开关的独立开关控制
- 高低侧开关的独立开关控制
- 高低侧开关的独立开关控制
- 用于模拟电压测量的多路复用的输出缓冲器
- 爆管引脚使用的减震装置并不需要保护ASIC不受由于动态短路或者接地而产生的基板插入效应所对其部署所带来的影响
- 用于公制比例爆管电阻测量的连接至微处理器 **ADC** 电源的外部引脚。
- 除 **GNDx**、**AGND**、**DGND**、**VCC5**、**VDDIO** 以及 **AMX_OUT** 外的所有引脚都支持 **40 V** 引脚功能
- 工作环境温度范围: **-40°C** 至 **105°C**

- 散热增强型 **48** 引脚 **TSSOP DCA PowerPad** 封装

应用

- 气囊应用的爆管驱动器


PRODUCT PREVIEW

说明

TPIC71008是一款适用于汽车用气囊部署的8通道爆管驱动器。每个通道包括高侧与低侧开关，所提供的独立控制逻辑可防止不慎部署。高侧与低侧开关都支持内部电流限制与过温保护。

IC 寄存器可用于8通道配置、控制与状态监控。为了避免不慎部署，高低侧开关只有在采用适当配置排序、两个独立布防安全输入 (arming/safing input) 为活动状态且部署控制器逻辑的多个输入达到标准水平时才可打开。该寄存器采用串行通信接口编程。



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PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

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English Data Sheet: **SLVSAX3**

为了避免能耗过大，每通道最大工作 ON 时间由可编程点火定时器限定。此外，还可使用电流限制寄存器在部署时通过开关对最大电流进行编程。低侧开关上的电流限制高于相应高侧开关。部署过程中，低侧开关将全面增强，可在 RDS_ON 模式下工作，而高侧开关则在电流调节模式下工作。

IC 诊断功能可监控部署引脚电压，这使得高侧开关测试、低侧开关测试、爆管电阻测量、爆管电池或接地漏电测量或者任何爆管通道的漏电测量。爆管漏电测量不需要出现爆管负载，其包含 Zx 和 ZMx 引脚。诊断信息通过 AMX_OUT 引脚（针对模拟信号）与 SPI 映射状态寄存器（针对数字内核锁存的状态信号）进行通信。

高侧与低侧爆管驱动器都具有诊断级电流限制与部署级电流限制。默认的高侧及低侧爆管驱动器电流限制为诊断级电流限制。所有高侧驱动器的高侧开关部署电流限制都可通过 SPI 映射寄存器和器件 EEPROM 设置（见表 1）设为 1.2 A（最小值）或 1.75 A（最小值）（见表 2）。低侧部署电流限制不可编程，固定为大于高侧驱动器电流限制水平。每个不同爆管驱动器的接通时长可通过 SPI 映射寄存器进行编程。

部署排序需要一系列特定的软件命令与外部硬件安全防护逻辑输入（TZ=H，IWD=L）相结合来提供部署功能。高侧与低侧驱动器的打开排序可通过 SPI 命令进行软件控制。关闭程序可通过为高侧驱动器部署 ASIC 自动控制，而低侧驱动器的关闭程序则可通过部署 ASIC 进行控制，或通过 SPI 命令由软件控制。编程的接通时间部署后，高侧驱动器首先关闭，随后是低侧驱动器在大约 100us 后关闭（针对硬件控制关闭排序器件配置而言），或在 SPI 命令后，外部微处理器一直在接收低侧驱动器的关闭信息（针对软件控制关闭排序器件配置而言）。

RESET_N 是活动低输入复位信号。一旦外部电压电源处于特定限制范围，该输入便由供电单元和 / 或外部微控制器中的较高值释放。通过串行通信接口配置和控制器件，需要外部微处理器。可靠的软件对系统工作非常重要。

表 1. 典型点火电流的潜在部署设置

点火电压	VZX 和 ZX 引脚之间实现部署的最大平均点火电压	典型点火电流	停留（点火）时间
35 V	32.56 V	1.2 A	2 ms ⁽¹⁾
35 V	35.0 V	1.75 A	0.5 ms ⁽¹⁾

(1) 对编程所需的停留（点火）时间而言

延长部署时间会激活过温保护电路并终止部署。如果在部署时短路至接地的情况发生时，则在整个 HS_FET 上完全下降 35 V 点火电压，这将启动热关闭保护机制来保护器件。

表 2. 最大点火电流的潜在部署设置

点火电压	VZX 和 ZX 引脚之间实现部署的最大平均点火电压	最大点火电流 ⁽¹⁾	停留（点火）时间
35 V	30 V	2.6 A (for 1.75 A 电流设置)	0.7 ms ⁽²⁾
35 V	31 V	2.0 A (for 1.2 A 电流设置)	2.0 ms ⁽²⁾

(1) 最大点火电流级别可通过器件 EEPROM 设置设定

(2) 对编程所需的停留（点火）时间而言

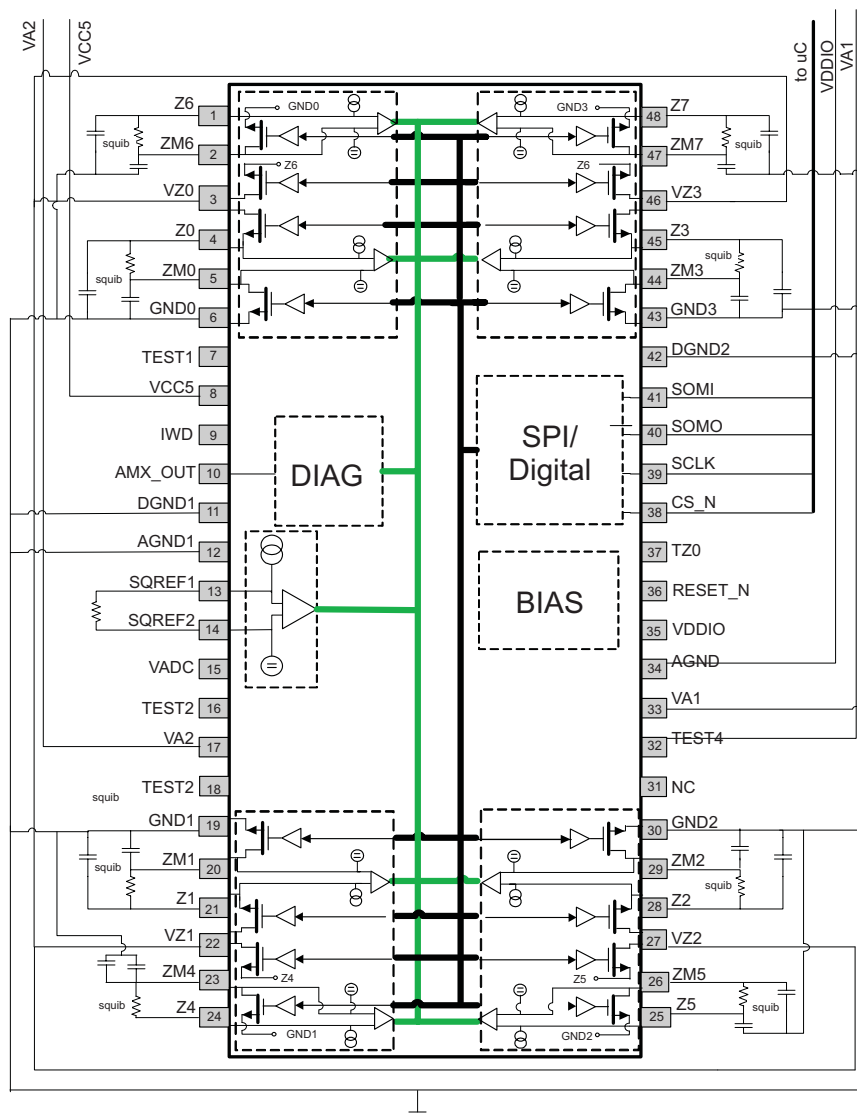


图 1. 功能方框图

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ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	HTSSOP – DCA	Tape and reel	TPIC71008TDCAQ1	TPIC71008
			TPIC71008TDCARQ1	

- (1) "Pb-Free" is defined to be compliant with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials unless exempt. Where designed to be soldered at high temperatures, TI "Pb-Free" and "RoHS Compliant" products are suitable for use in specified lead-free processes.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPIC71008TDCARQ1	Active	Production	HTSSOP (DCA) 48	2000 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 105	TPIC71008T
TPIC71008TDCARQ1.A	Active	Production	HTSSOP (DCA) 48	2000 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 105	TPIC71008T

- ⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).
- ⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- ⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- ⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- ⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- ⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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GENERIC PACKAGE VIEW

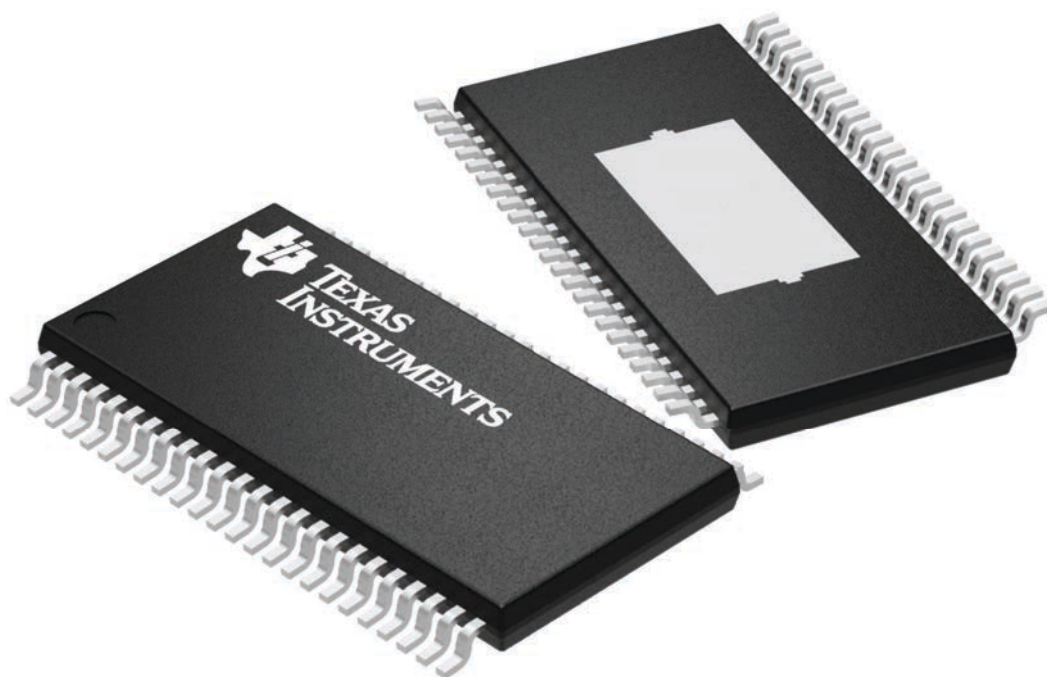
DCA 48

HTSSOP - 1.2 mm max height

12.5 x 6.1, 0.5 mm pitch

SMALL OUTLINE PACKAGE

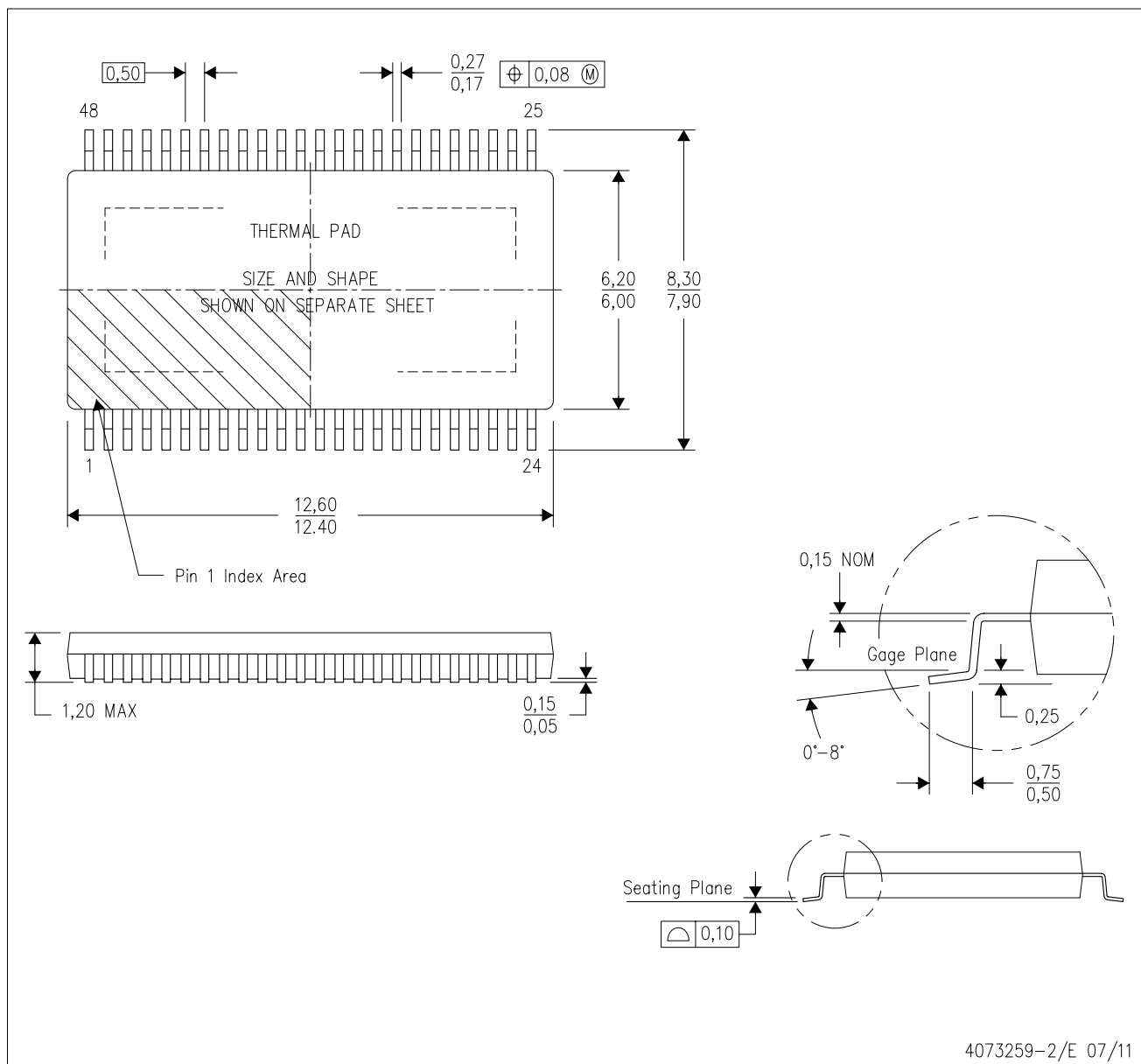
This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224608/A

DCA (R-PDSO-G48)

PowerPAD™ PLASTIC SMALL-OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - F. Falls within JEDEC MO-153

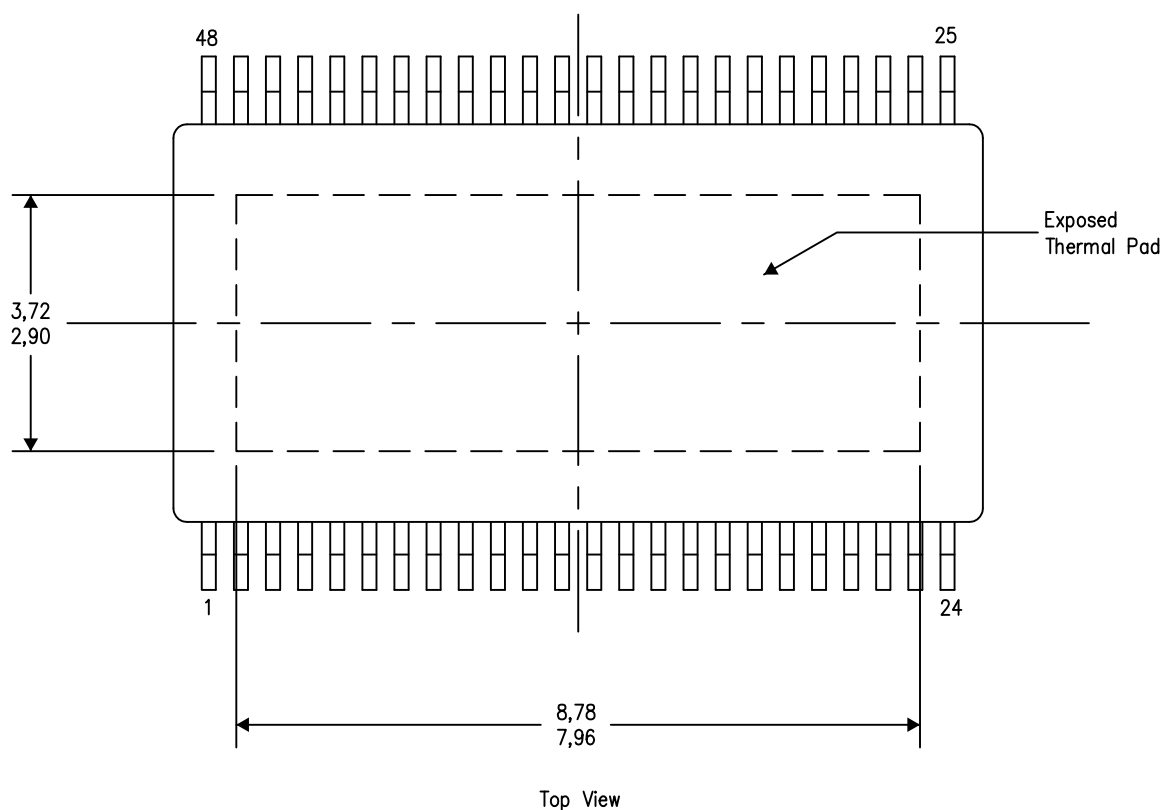
PowerPAD is a trademark of Texas Instruments.

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Exposed Thermal Pad Dimensions

4206320-7/S 11/14

NOTE: A. All linear dimensions are in millimeters

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